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## PATENT ABSTRACTS OF JAPAN

(11)Publication number:

64-054749

(43)Date of publication of application: 02.03.1989

(51)Int.Cl.

H01L 23/28 H01L 21/60

H01L 23/50

(21)Application number: 62-211993

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(22)Date of filing:

26.08.1987

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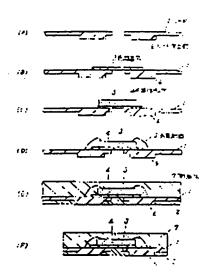
KIKUCHI TATSUO TAKASE YOSHIHISA

### (54) SEMICONDUCTOR DEVICE AND MANUFACTURE THEREOF

PURPOSE: To obtain a highly accurate and highly reliable semiconductor device by placing a semiconductor chip through an insulating substrate on one group of highly accurate metal leads, connecting the leads to fine

metal wirings, and transfer molding them.

CONSTITUTION: A thin resin plate 3 is attached to leads 1 having protrusions 6, and electrodes on a semiconductor chip 4 are connected to the leads 1 by fine metal wirings 5. Then, the leads except the protrusions 6 are sealed with resins 2, 7, shape and size are determined and cut. According to this structure, a small-sized and thin semiconductor device having high dimensional accuracy and reliability is obtained without complicated structure like a both-side substrate only by employing metal leads of special shape at part, and is freferably adapted for an IC.



#### LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration)

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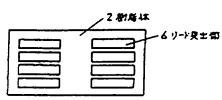
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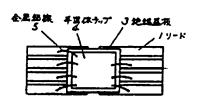
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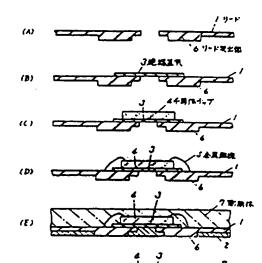
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